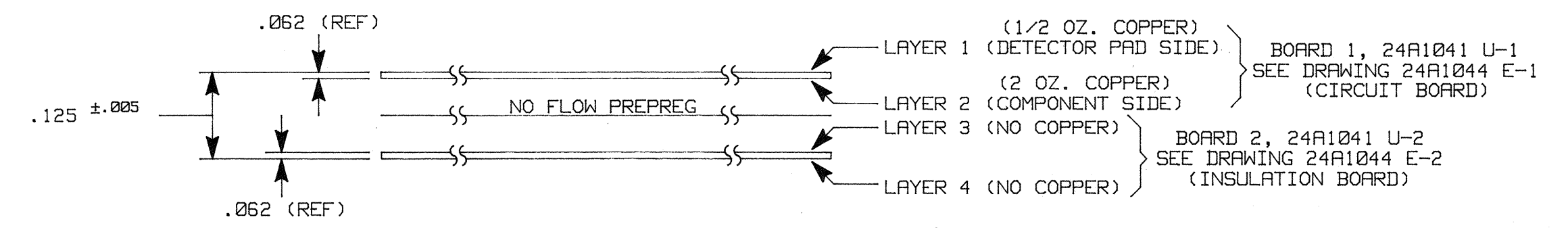


VIEWED FROM CONNECTOR SIDE
WITH INSULATION BOARD

NOTES:

- BOARD MATERIAL: (4 LAYER BOARD)
 - BOARD 1 (CIRCUIT BOARD) - GLASS EPOXY LAMINATE TYPE NEMA G10, .062 THICK PER MIL-P-13949G FL-GEN 062C-2/.5-B1B (2 OZ. COPPER FOR LAYER 2 AND 1/2 OZ. COPPER FOR LAYER 1).
 - BOARD 2 (INSULATION BOARD) - GLASS EPOXY LAMINATE TYPE NEMA G10, .062 THICK PER MIL-P-13949G FL-GEN 062C-.5/.5-B1B (1/2 OZ EACH SIDE, ETCHED AWAY).
- THERE IS BE TIN PLATING ONLY ON LAYER 2 ON SMT CONNECTOR PADS. THERE IS TO BE NO TIN PLATING THROUGH HOLES. SEE DRAWING 24A1044 E-3.
- FINISHED BOARD THICKNESS TO BE .125 +/- .005. OVER-ALL DIMENSIONS FOR BOARD ARE 26.000W X 29.000H. DIMENSIONS ARE IN INCHES.
- PREPREG TO BE NO FLOW TYPE.
- ARTWORK TO BE PLOTTED ON GLASS FOR REGISTRATION ACCURACY.
- REFERENCE DRAWINGS:

24A1044 E-1	a000886e1	HOLE SCHEDULE - CIRCUIT BOARD
24A1044 E-2	a000886e2	ROUTING SCHEDULE - INSULATION BOARD
24A1044 E-3	a000886e3	ARTWORK - TIN PLATING



I:		TITLE		STAR TPC	
II:				INNER SECTOR	
III:				PAD PLANE INNER SECTOR BOARD - 2 LAYER	
SHOWN ON				BOARD OUTLINE (a000886u1)	
PROJECT NUMBER	8052-24	DRAWN	STIRKKINEN	DATE	09/13/93
SERIAL NUMBER		CHECKED		DATE	
DATE ISSUED		APPROVED		DATE	
DATE RECD.		ENGINEER	THOMAS NOGGLE	FILE NO.	a000886m1
DEL. TO		SCALE	NONE	SIZE	4
				DRAWING NO.	24A1044 M-1
				REV.	
					SHEET 1 OF 1
					E2, E7
					FRED BRESER 10/21/94
					OCTOBER 20, 1994